

METHOD FOR SUPPLYING SLURRY TO POLISHING APPARATUS

ABSTRACT OF THE DISCLOSURE

A method for feeding slurry and a slurry feeder capable of feeding slurry to a chemical mechanical polishing apparatus. The slurry is fed from the slurry supply tank for storing the slurry at a given concentration to the chemical mechanical polishing apparatuses by a slurry feed pumps. The operations of the slurry feed pumps are suspended during the period of time other than during the time of feeding the slurry to the chemical mechanical polishing apparatuses. A slurry feeder for feeding a slurry to the polishing apparatus includes a pump for feeding the slurry at a flow rate  $Q$  from a slurry supply tank to the polishing apparatus. When the given sedimentation velocity of the given slurry is indicated by  $V$ , the horizontal sectional area of the slurry supply tank is set to become smaller than  $Q/V$ .

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